

forming abrasive boehmite particles by dipping particles of aluminum in heated water with sodium aluminate added thereto;

creating a slurry containing said abrasive boehmite particles; and

F2
cont planarizing at least one film formed on a substrate by employing a chemical-mechanical polishing process using said slurry.

F3 25. A polishing process according to claim 22, wherein said slurry used in said chemical-mechanical polishing process is a basic slurry.

26. A polishing process according to claim 25, wherein said step of creating a slurry comprises suspending said boehmite particles in a solution containing KOH, water, and an alcohol.

REMARKS

This is a full and timely response to the non-final Official Action mailed August 10, 2000. Reexamination and reconsideration in light of the above amendments and the following remarks are courteously requested.

By the foregoing amendment, claims 12, 22, and 25 to 26 been amended. Additionally, claim 21 has been canceled.